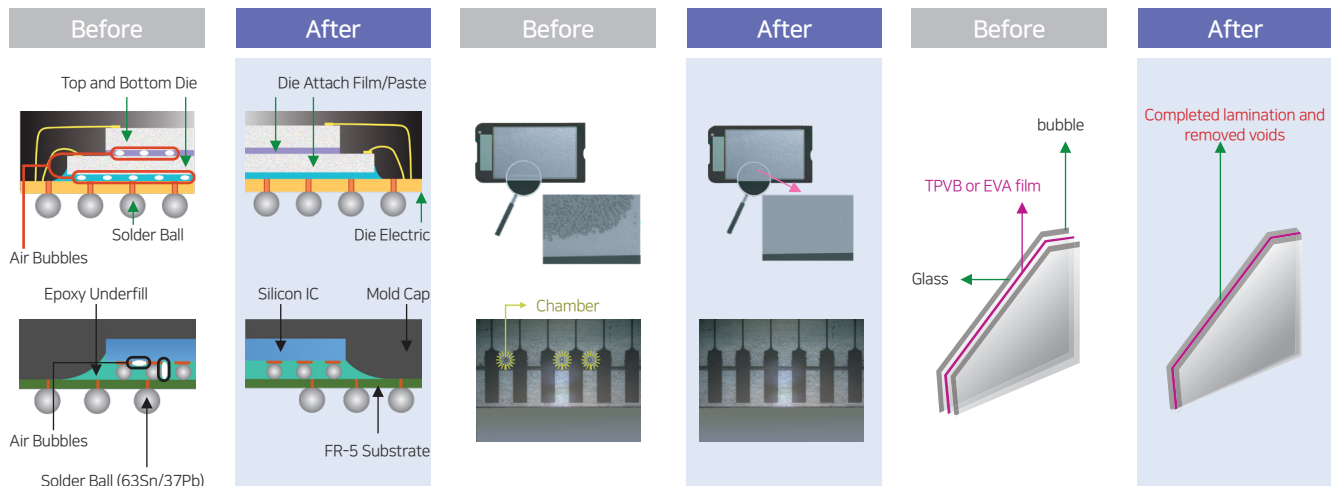
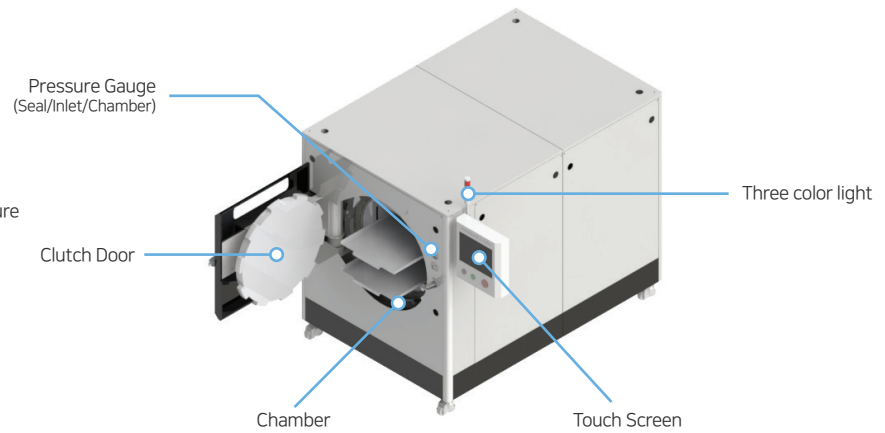


Pressure Oven

It has application for lamination and to remove voids both layers in industries of touch panel and LCD, PDP, Semi conductor

FEATURE

- ① Effect of removing voids by pressure and temperature
- ② Effect of hardness by temperature
- ③ Effect of adhesive strength by pressure



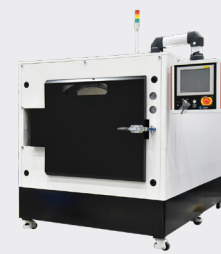
Touch panel screen, Film(FA)



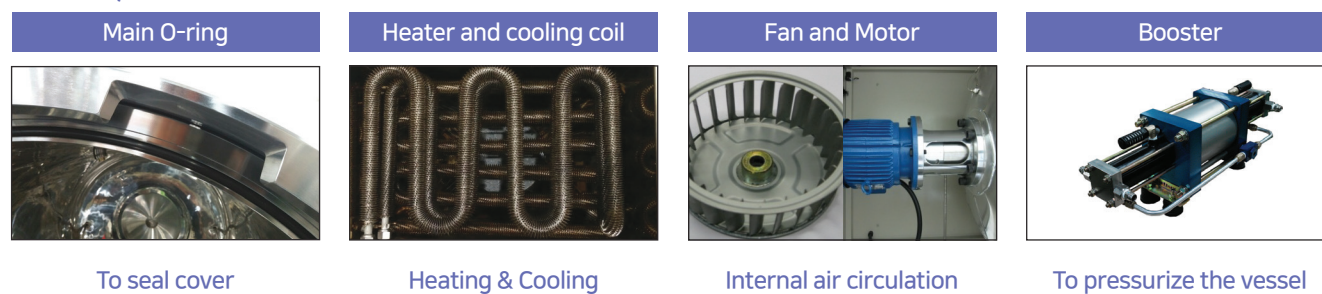
Glass (GA)



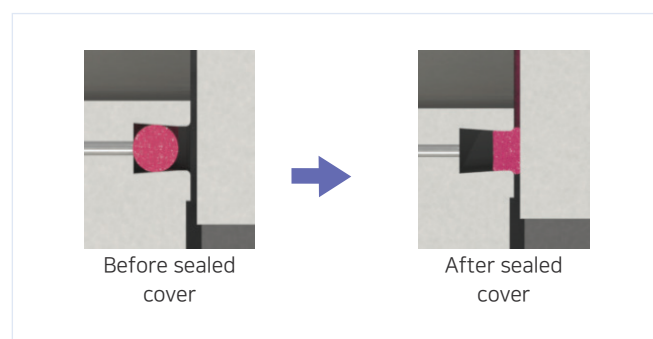
Semiconductor of package process (HA)



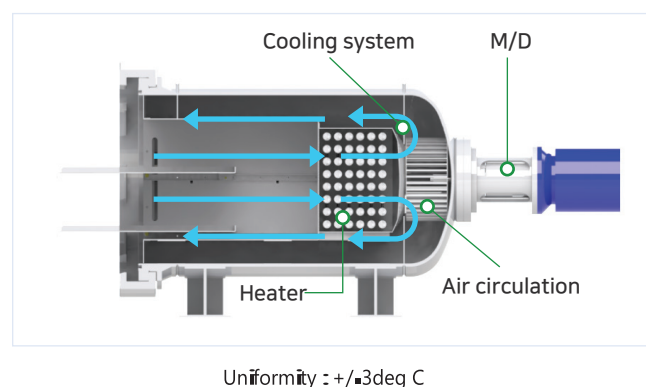
Part of System



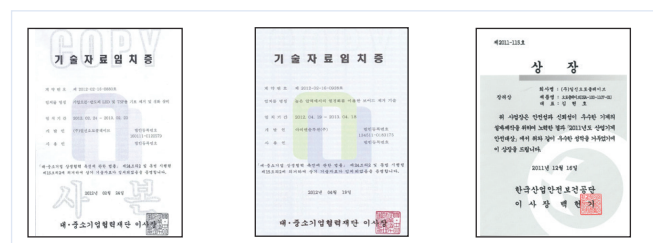
Main O-ring



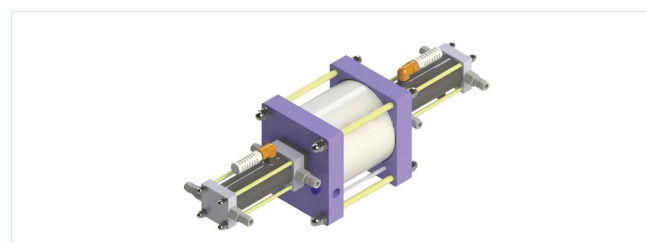
Internal air flow



Award for safety

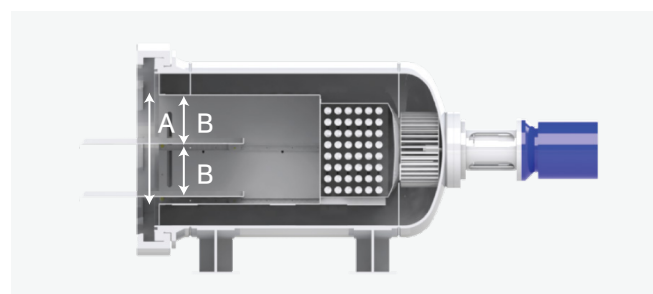


Booster



- 1 Compacted size
- 2 Reasonable price
- 3 Durability

CONSIDERATION TO ORDER



- 1 Size (A,B)
- 2 Pressure
- 3 Temperature
- 4 Cooling
- 5 Booster or Compressed air
- 6 Gas Media(Air or Gas)